Koh Young Technology Brings Proven 3D Metrology Expertise to the Advanced Packaging Stage at ECTC 2026

The Inspection Leader that Transformed SMT is now Solving Advanced Packaging's Toughest Challenges

Atlanta, GA — Koh Young, the industry leader in True3D™ measurement-based inspection solutions, is bringing its battle-tested platform to where that challenge is being solved at the 2026 IEEE Electronic Components and Technology Conference (ECTC), May 26–29, at the JW Marriott & The Ritz-Carlton Grande Lakes in Orlando, Florida. The advanced packaging industry is demanding a level of inspection precision that traditional metrology simply cannot deliver, and Koh Young is ready to meet that moment.

A Proven Platform. A New Frontier.

Koh Young's True3D™ technology didn't become the global standard in electronics manufacturing inspection by accident. It earned that position by delivering measurement accuracy, process intelligence, and yield improvements that manufacturers could measure and depend on. Now, that same platform is being applied to the complexity of advanced packaging, including heterogeneous integration, wafer-level packaging, and semiconductor inspection, where the margin for error is even smaller and the cost of failure even greater.

As the exclusive sponsor of the ECTC Gala, Koh Young is making a clear statement: this community matters, and we are here for the long term. The 2026 technical program spans assembly and manufacturing technologies, heterogeneous integration, wafer-level packaging, and semiconductor inspection, reflecting exactly the challenges our solutions are engineered to address.

See It for Yourself at Booth 208

Talk is cheap. At Booth 208, Koh Young's specialists will show, not just tell, how AI-powered 3D inspection is solving real problems in advanced packaging production. See how True3D™ measurement and automated process control help manufacturers improve quality, reduce waste, and build toward zero-defect production. If you're wrestling with yield loss, process drift, or inspection gaps in your advanced packaging line, this is a conversation worth having.

Making the Case for a New Standard

"Advanced packaging is pushing the boundaries of what inspection and metrology have traditionally been asked to do," said Joel Scutchfield, General Manager of Surface Mount & Advanced Packaging Operations at Koh Young America. "We built the inspection standard in SMT by delivering measurement accuracy and process intelligence that manufacturers could actually depend on. Now we're bringing that same rigor and commitment to zero-defect manufacturing to advanced packaging. ECTC 2026 is where we make that case directly to the engineers and decision-makers who need it most."

Join the Conversation

Register for ECTC 2026 and make Booth 208 a priority stop. To learn more about Koh Young's inspection solutions for advanced packaging and semiconductor applications, visit www.kohyoungamerica.com.

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About Koh Young Technology, Inc.

Founded in 2002, Koh Young pioneered the industry's first 3D Solder Paste Inspection (SPI) system using patented dual projection Moiré technology. Today, it leads the market in 3D SPI and Automated Optical Inspection (AOI) solutions, with over 26,500 systems installed globally at over 4,100 customers. Koh Young's True 3D technology addresses challenges in electronics manufacturing including surface mount, through-hole, pin insertion, conformal coating, machined parts, semiconductor wafers, and advanced packaging. Guided by user-focused R&D, the company continues to innovate and address evolving market needs. With headquarters in Korea and regional offices worldwide, Koh Young remains close to its customers, delivering trusted solutions for smart manufacturing. Visit www.kohyoungamerica.com to learn more.